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Large anisotropic single crystal epitaxial graphene flakes isolated from SiC wafers

Sofia Aslanidou^{1,2}, Alberto García-García¹, Elisabet Prats¹, Philippe Godignon¹, Gemma Rius¹

1 Institute of Microelectronics of Barcelona, IMB-CNM, CSIC, 08193, Bellaterra, Spain 2 Universitat Autònoma de Barcelona, UAB, 08193, Bellaterra, Spain

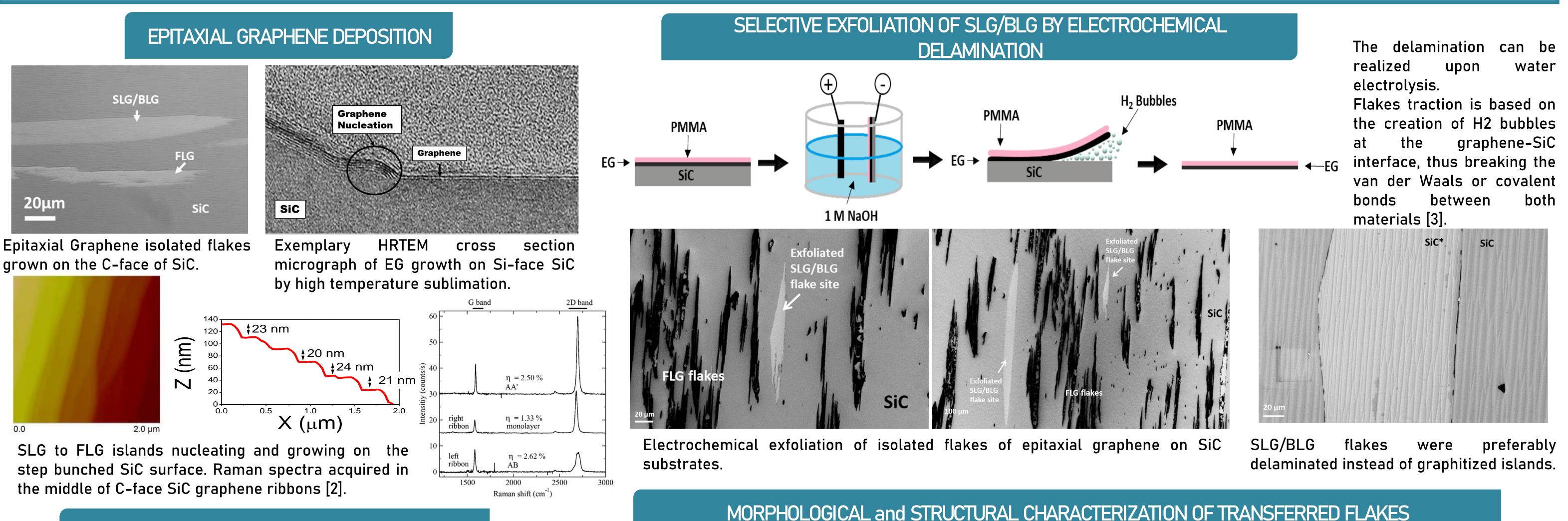
INTRODUCTION

High performance graphene electronic devices require high quality graphene obtained either by CVD on Cu foils or epitaxial graphene (EG) on SiC^[1]. In this work, we report some preliminary results on the development of electrical devices based on large anisotropic single crystal EG flakes obtained on the C-face of SiC by high temperature sublimation^[2]. The EG flakes were transferred to SiO₂ substrate via PMMA-assisted electrochemical delamination technique^[3] and electrical contacts were aligned and patterned by e-beam lithography and lift-off process. Both structural and electronic characterization indicate that high crystalline quality of EG is basically preserved upon electrochemical transfer as well as device fabrication.



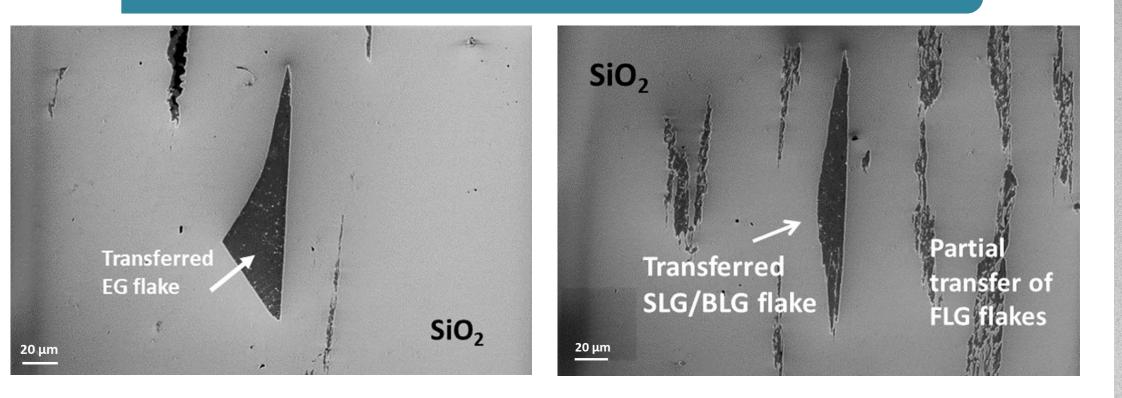
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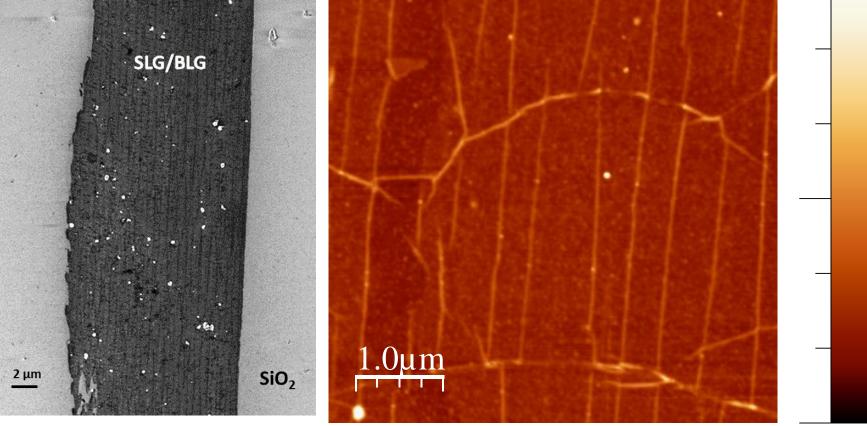


EPITAXIAL GRAPHENE FLAKE TRANSFER

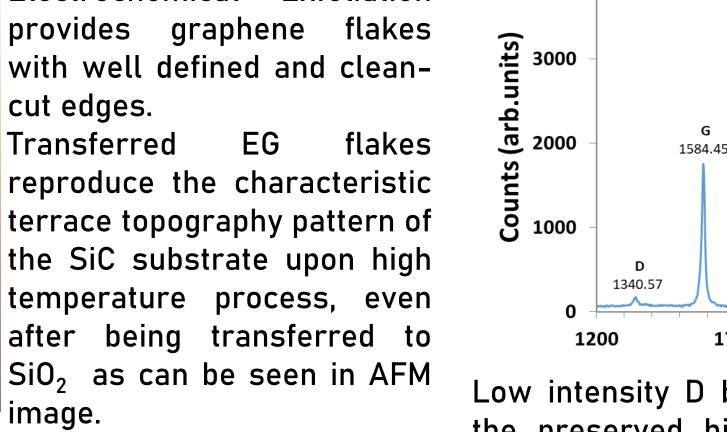
Electrochemical Exfoliation



SEM images displaying the results of transfer. Integral SLG/BLG flakes are transferred on SiO₂ substrate. Partial FLG flakes can be transferred too, but typically they present structural damage or tend to be broken.



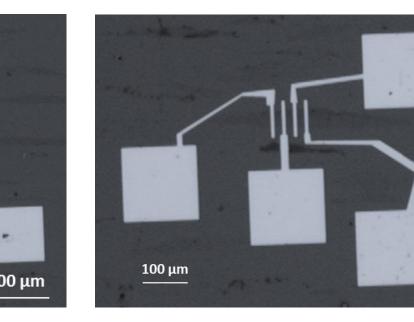
Graphene



2200 2700 1700 Raman Shift (cm-1) Low intensity D band and $I_{2D}/I_{G}\sim2$ indicate the preserved high quality of monolayer epitaxial graphene, confirming the preservation of crystal quality upon delamination from SiC and transfer.

EPITAXIAL GRAPHENE FABRICATION of ELECTRONIC DEVICES

100 µm



Device 1

Device 2

Device 3

Specific SLG flakes were identified, localized and electricallyinterfaced with dedicated metal contact designs.

Three electronic devices were realized and electrically characterized. The electrical contacts were aligned and patterned simply by using ebeam lithography, thin film evaporation and resist lift off process.

RESULTS of PRELIMINARY ELECTRICAL CHARACTERIZATION

• Electrical characteristics are based on 4-probe technique.

• The linear I-V relationship confirms the obtaining of ohmic contacts.

	V2-V1 Linear Fit		R _{Sheet} (kΩ)		R _{Contact} (kΩ)	
600 - 500 - 500 -		Device	Positive I/V branch	Negative I/V branch	Positive I/V branch	Negative I/V branch
(100 - س 100 - 100 - 100 - 200 - 200 -		1	0.45	0.46	1.93	1.72
- 100 - - 0 -	Equation y = a + b*x Plot V2-V1 Weight No Weighting Intercept 2.55851 ± 0.26975 Slope 2.83206 ± 0.00232 Residual Sum of Squares 175.62634 Pearson's r 0.99997 R-Square (COD) 0.99993 Adj. R-Square 0.99993	2	0.45	0.45	1.18	1.19
	0 50 100 150 200 I2-I1 (μA)	3	0.38	0.39	1.71	2.34

FUTURE WORK

The results presented in this poster are a preliminary study for the realization and application of epitaxial graphene in electronic devices.

Further electrical tests will be performed for the precise evaluation of the electronic properties and potential electrical characteristics of the devices. Back gated devices will be used in order to determine carrier' mobilities. Finally, Reconfigurable devices based on epitaxial graphene could be achieved adding top-gate structure.

Obtained values are aligned with results reported in the literature for epitaxial graphene [4]. Our devices could be easily further improved by applying suitable treatments prior to metal deposition, such as plasma treatments [5] of the contact areas or post deposition treatments such as rapid thermal annealing [6].

ACKNOWLEDGMENTS

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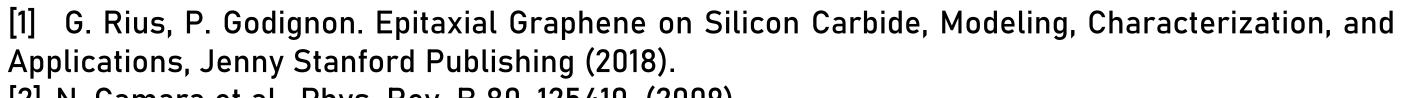
CONTACT PERSON

Sofia Aslanidou

sofia.aslanidou@imb-cnm.csic.es

PhD Student IMB-CNM-CSIC PDS Group

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Electrical

Contacts

